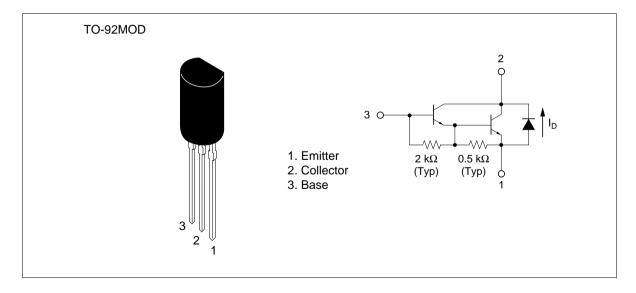
Silicon NPN Epitaxial, Darlington

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#### Application

- Low frequency power amplifier
- Complementary pair with 2SB1387

#### Outline





## **Absolute Maximum Ratings** (Ta = $25^{\circ}$ C)

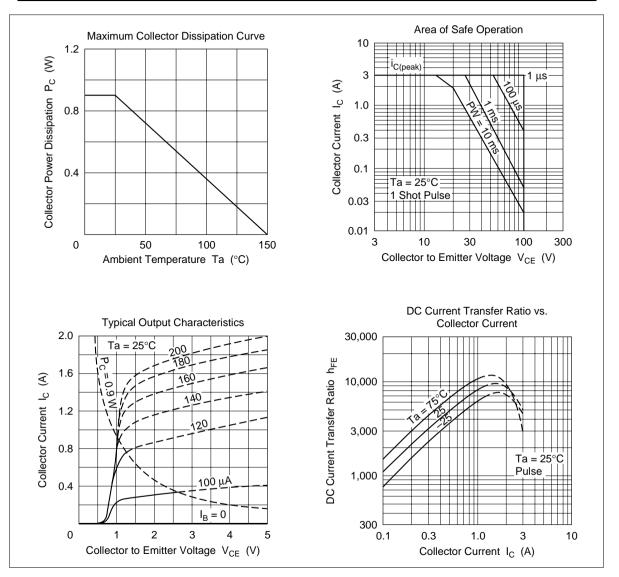
Item	Symbol	Ratings	Unit
Collector to base voltage	V <sub>CBO</sub>	120	V
Collector to emitter voltage	V <sub>CEO</sub>	120	V
Emitter to base voltage	V <sub>EBO</sub>	7	V
Collector current	Ι <sub>c</sub>	1.5	А
Collector peak current	ic <sub>(peak)</sub>	3.0	А
Collector power dissipation	Pc	0.9	W
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55 to +150	°C
E to C diode forward current	I <sub>D</sub>	1.5	А

#### **Electrical Characteristics** (Ta = 25°C)

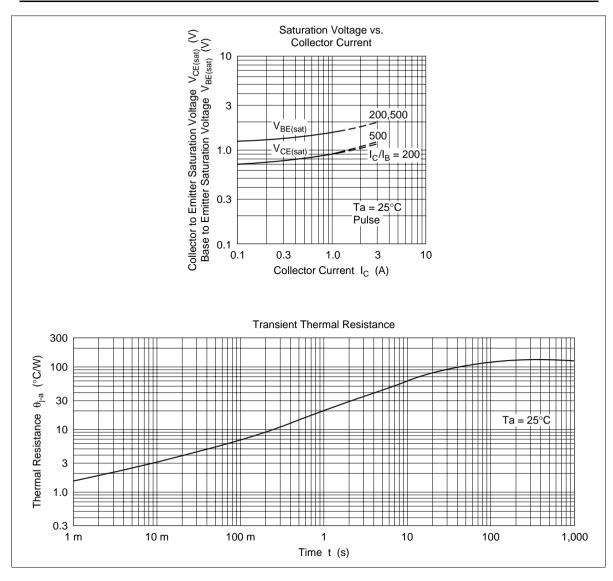
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Collector to base breakdown voltage	$V_{\rm (BR)CBO}$	120	_	_	V	$I_{c} = 0.1 \text{ mA}, I_{E} = 0$
Collector to emitter breakdown voltage	$V_{\rm (BR)CEO}$	120	—	—	V	$I_c = 10$ mA, $R_{\scriptscriptstyle BE} = \infty$
Emitter to base breakdown voltage	$V_{(BR)EBO}$	7	_	_	V	$I_{\rm E} = 50$ mA, $I_{\rm C} = 0$
Collector cutoff current	I <sub>CBO</sub>	_	_	1.0	μΑ	$V_{CB} = 100 \text{ V}, \text{ I}_{E} = 0$
	I <sub>CEO</sub>	—	—	10	μΑ	$V_{CE}$ = 100 V, $R_{BE}$ = $\infty$
DC current transfer ratio	$h_{\text{FE}}$	2000	—	30000		$V_{ce} = 3 V, I_c = 1 A^{*1}$
Collector to emitter saturation voltage	$V_{\text{CE(sat)1}}$	—	—	1.5	V	$I_{c} = 1 \text{ A}, I_{B} = 1 \text{ mA}^{*1}$
	V <sub>CE(sat)2</sub>	—	—	2.0	V	$I_{c} = 1.5 \text{ A}, I_{B} = 1.5 \text{ mA}^{*1}$
Base to emitter saturation voltage	V <sub>BE(sat)1</sub>	_	_	2.0	V	$I_{c} = 1 \text{ A}, I_{B} = 1 \text{ mA}^{*1}$
	$V_{\text{BE(sat)2}}$	—	—	2.5	V	$I_{\rm C} = 1.5 \text{ A}, I_{\rm B} = 1.5 \text{ mA}^{*1}$
E to C diode forward voltage	V <sub>D</sub>		_	3.0	V	$I_{\rm D} = 1.5 \ {\rm A}^{*1}$

Note: 1. Pulse test

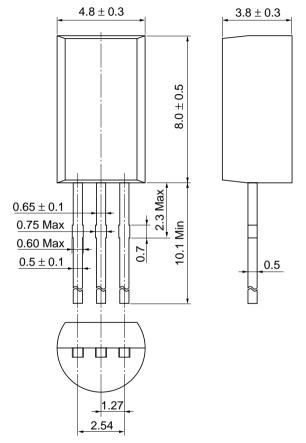
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#### Unit: mm



Hitachi Code	TO-92 Mod
JEDEC	_
EIAJ	Conforms
Weight (reference value)	0.35 g

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